Kingbright

3.5 x2.8mm SMD CHIP LED LAMP

Part Number: APED3528MGC Mega Green

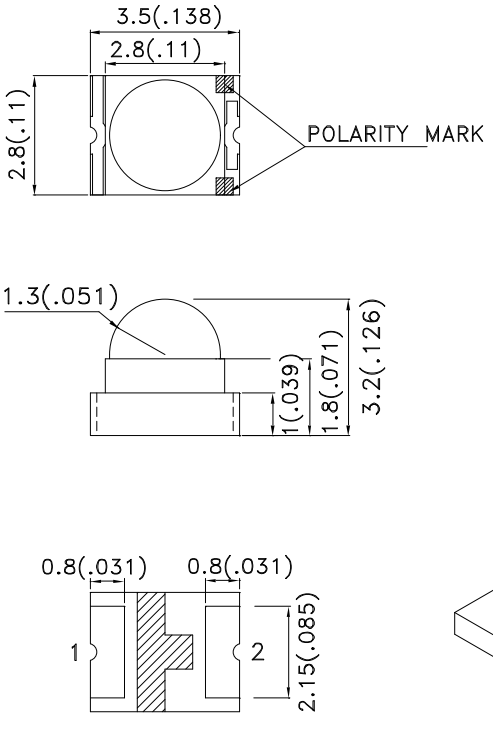
Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Ideal for backlighting.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Mega Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.008") unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APED3528MGC	Mega Green (AlGaInP)	WATER CLEAR	70	250	40°

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

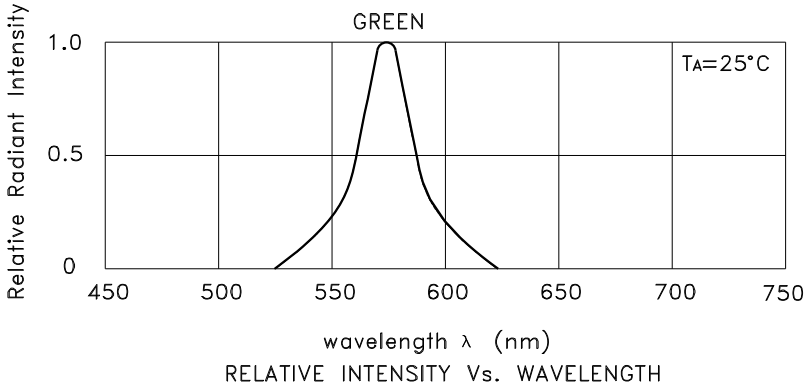
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	I_F=20mA
λD [1]	Dominant Wavelength	Mega Green	570		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	I_F=20mA
C	Capacitance	Mega Green	20		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Mega Green	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Mega Green		10	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

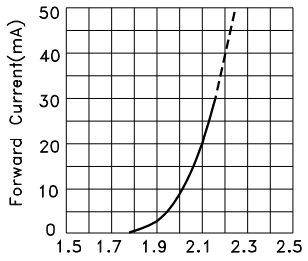
Parameter	Mega Green	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

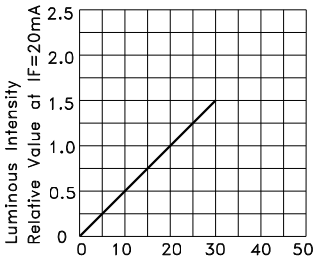


RELATIVE INTENSITY Vs. WAVELENGTH

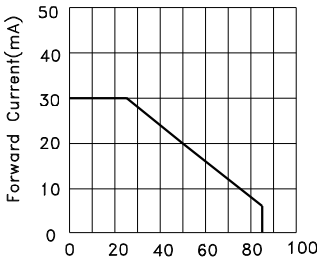
Mega Green **APED3528MGC**



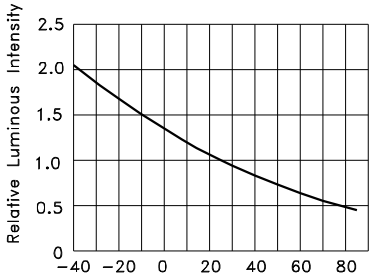
FORWARD CURRENT Vs.
FORWARD VOLTAGE



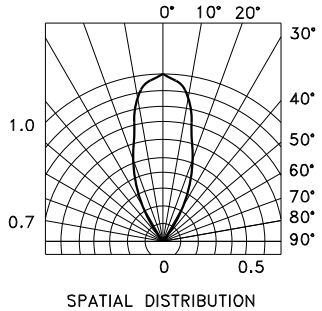
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

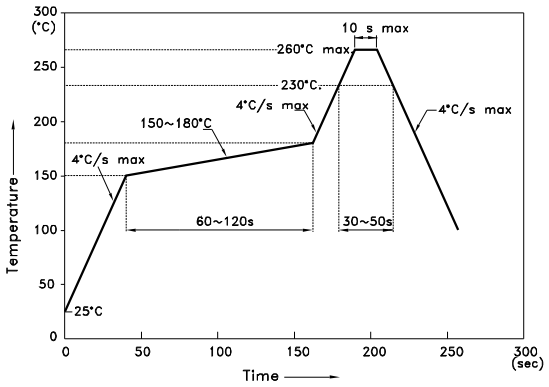


SPATIAL DISTRIBUTION

APED3528MGC

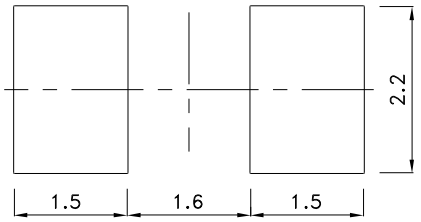
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

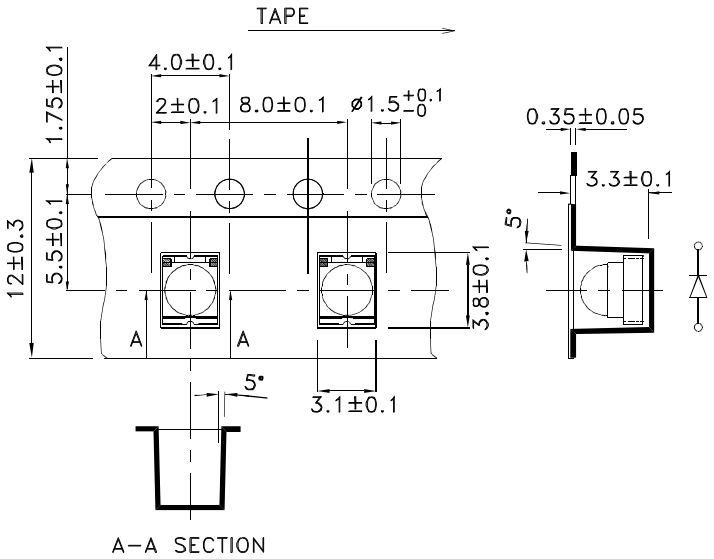


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



Tape Dimensions
(Units : mm)



PACKING & LABEL SPECIFICATIONS **APED3528MGC**